

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-7 (Canceled).

8. (Currently Amended) [[An]] The earphone system of claim 9 or 10 wherein said output terminal is for use in a terminal of a mobile communication equipment, wherein said earphone system is provided with said high-frequency current suppressor as claimed in any one of claims 1 through 4.

9. (Currently Amended) An earphone system comprising a connection plug connected to an output terminal of an electronic equipment, an earphone, and a signal cable for connecting said connection plug with said earphone, wherein a high-frequency current suppressor consisting of soft magnetic material is added at least partially to any one of said connection plug, said

earphone, and said signal cable, ~~which is consisting and~~  
consists of composite magnetic material selected from material  
groups ~~consisting of as follows:~~

(a) [[the]] a material which comprises soft magnetic powder obtained by flattening alloy powder including at least Fe, Si, Al, and binding material;

(b) [[the]] a material which comprises soft magnetic powder obtained by flattening alloy powder including at least Ni, Fe, and binding material; and

c) [[the]] a magnetic loss thin film which comprises a first member consisting of at least any one of Fe, Co, Ni, or mixture thereof and a second member consisting of insulating material including at least more than one kind of element other than said Fe, Co, Ni.

10. (Original) An earphone system as claimed in claim 9, wherein a part or a whole of outer circumference of said signal cable is covered by said high-frequency current suppressor.

11. (Original) An earphone system as claimed in claim 9 or 10, wherein a part or a whole of outer circumference of an outer conductor of said signal cable is covered by said high-frequency current suppressor.

12. (Previously Presented) An earphone system as claimed in claims 9 or 10, wherein said high-frequency current suppressor is provided near a portion where said signal cable and said earphone are connected to each other.

13. (Currently Amended) An earphone system as claimed in claims 9 or 10, wherein said high-frequency current suppressor is included provided inside said earphone.

14. (Previously Presented) An earphone system as claimed in claims 9 or 10, wherein said earphone system further comprises a microphone.

15. **(Currently Amended)** An earphone system as claimed in claim 14, wherein said high-frequency current suppressor is included provided inside said microphone.

16. **(Currently Amended)** An earphone system as claimed in claims 9 or 10, wherein a housing of said earphone ~~or said~~ microphone is formed by said high-frequency current suppressor.

17. **(Previously Presented)** An earphone system as claimed in claims 9 or 10, wherein said high-frequency current suppressor comprises composite magnetic material which comprises soft magnetic powder obtained by flattening alloy powder including at least Fe, Si, Al, and binding material.

18. **(Previously Presented)** An earphone system as claimed in claims 9 or 10, wherein said high-frequency current suppressor comprises composite magnetic material which comprises soft magnetic powder obtained by flattening alloy powder including at least Ni, Fe, and binding material.

19. (Currently Amended) An earphone system as claimed in claims 9 or 10, wherein said high-frequency current suppressor comprises said magnetic loss thin film which ~~comprises a first member including at least any one of Fe, Co, Ni, or mixture thereof and a second member including insulating material including at least more than one kinds of elements other than~~ said Fe, Co, Ni.

20. (New) An earphone system as claimed in claim 9 or 10, wherein said flexible member comprises a break which elongates over all length along an axial direction of said cable.

21. (New) An earphone system as claimed in claim 9 or 10, wherein said high-frequency current suppressor comprises at least two layers which consist of a high-frequency current suppressing layer and at least one outer layer.

22. (New) An earphone system as claimed in claim 21, wherein said outer layer is consisting of either a molded resin or a molded metal, or combination of said molded resin and said molded metal.

23. (New) An earphone system as claimed in claim 9 or 10, wherein said high-frequency current suppressor comprises said composite magnetic material which comprises soft magnetic powder obtained by flattening alloy powder including at least Fe, Si, Al, and binding material.

24. (New) An earphone system as claimed in claim 14, wherein a housing of said earphone or said microphone is formed by said high-frequency current suppressor.